



Bolzano, 22 Novembre 2024

Chips Revolution

Chips Mirror Group Italy & the Chips Act

Livio Baldi AEIT-AMES









- Chips Mirror Group Italy is the continuation of the ECSEL Mirror Group Italy: an organization including researchers from Italian industrial and academic institutions involved in the Chips JU programme:
 - To facilitate / coordinate the participation of Italian industrial and academic research organizations to the Chips Joint Undertaking (JU)
 - To promote the support by Italian Public Authorities,
 - ✓ To coordinate with similar initiatives in Europe.

Following the evolution of Microelectronics Joint Undertakings!



The Joint Undertakings (JU) for Microelectronics



JU are part of the Public-Private Partnerships (PPP): joint R&D&I initiatives among Commission, Member States and industrial/academic associations (AENEAS, INSIDE, EPOSS).

The funding from the Commission is matched by funding from Member States.

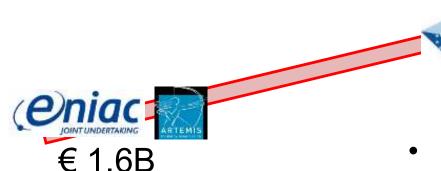
KDT JU

KEY DIGITAL

TECHNOLOGIES
JOINT LINDERTAKING

€ 3.6B

COVID 19 & Chips crunch



ECSEL JU € 2.2B

R&D&I agenda defined by private members, calls are agreed upon by private and public members.

2007

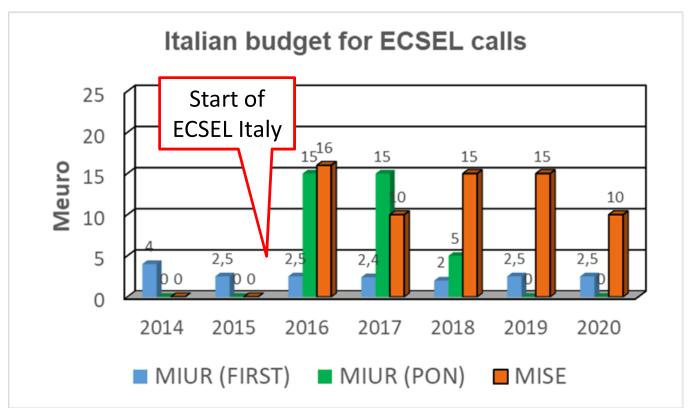
2014

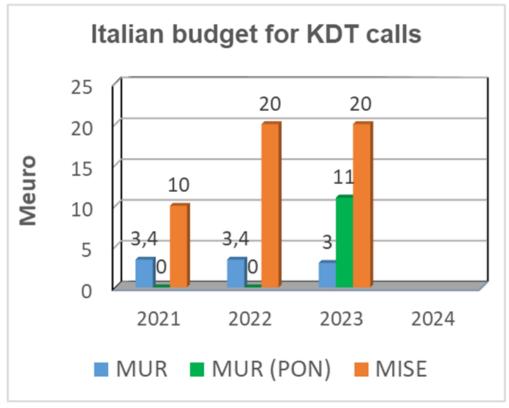
2021



Italian budget in ECSEL and KDT JU





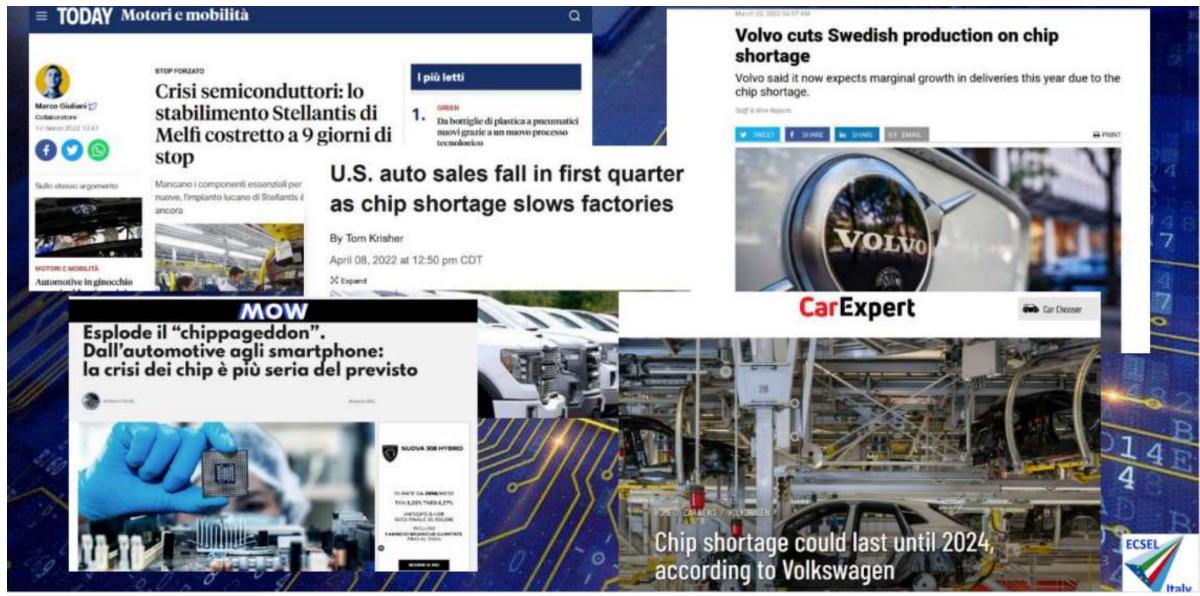


- In the period 2014-2020 (ECSEL JU), a total of 119.4 M€ were made available by MUR and MISE. For the KDT JU, 50 M€ from MIMIT, 9.8 M€ from MUR and 11 from PON funds.
- MUR and MIMIT have made available 22 M€ for the first calls of the Chips JU



The crisis of 2022

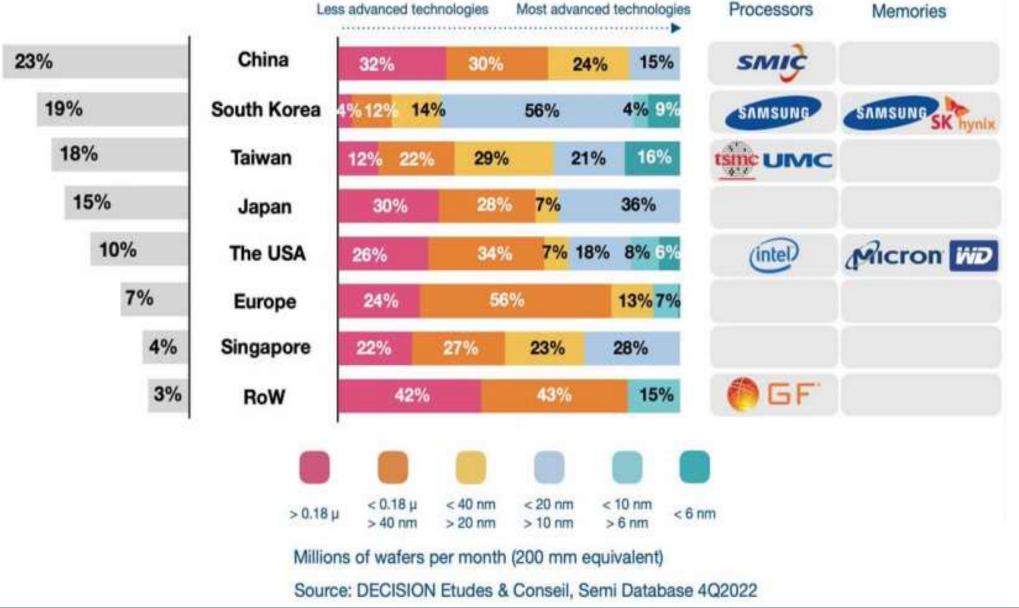






Semiconductor manufacturing

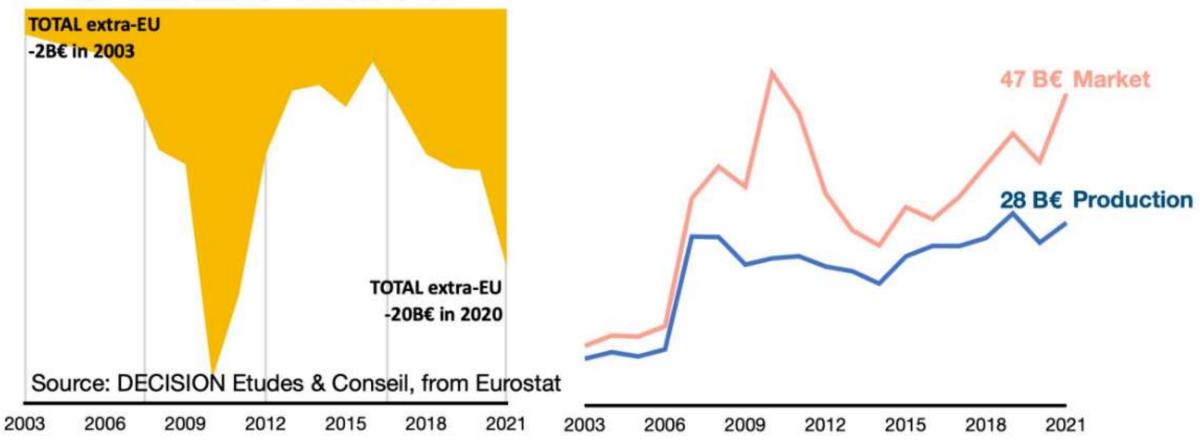














2022: European Chips Act





European Semiconductor Board (Governance)

Chips JU:

- Calls
- Pilot Lines
- CompetenceCenters

Pillar 1

Chips for Europe Initiative

- Initiative on infrastructure building in synergy with the EU's research programmes
- Support to start-ups and SMEs

Pillar 2

Security of Supply

 First-of-a-kind semiconductor production facilities

Attract new fabs in Europe

Pillar 3

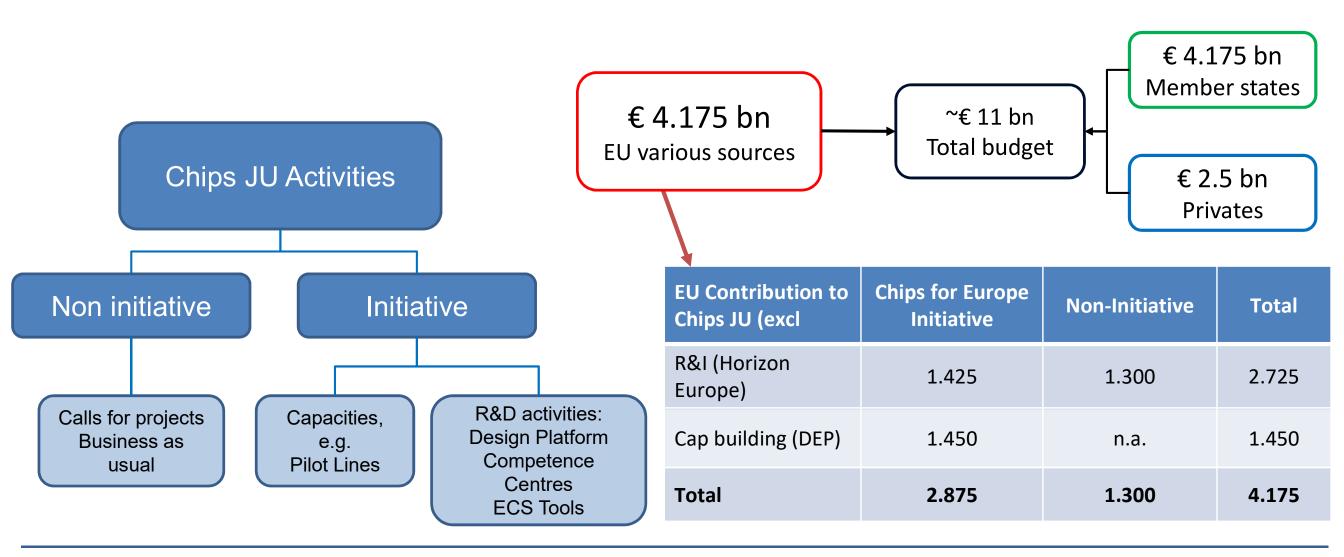
Monitoring and Crisis Response

- Monitoring and alerting
- Crisis coordination mechanism with MS
- Strong Commission powers in times of crisis











Initiative Activities



Pilot Lines



Public leading-edge facilities to support industry in developing, testing and validating new technologies and systems, and implementing prototypes.

Competence Centres



A network of competence centres, across Europe, to provide access to technical expertise and experimentation, to approach and improve design capabilities and developing skills

Design Platforms



A virtual environment, based on the cloud, available across the Union, integrating a wide range of design facilities from IP libraries to EDA tools and support services, for SME's and RTO's.





Non Initiative Activities

- Yearly call for projects in the field of Electronic Components and Systems.
- Calls open in February with a 1° deadline in April and the final one in September.
- Advertised by two events



ECS BROKERAGE

EVENT 2025

18-19 February

Aeneas

EPoss.

Lurgean Asacdation de Sinut Sydems belagration

Inside

Mostry, Association

EFECS 2024 is the European Forum for Electronic Components and Systems, brings together industry, policymakers and researchers. It offers the opportunity for networking and project presentation.

The ECS Brokerage Event combines the brokerage activities of the industry associations AENEAS, EPoSS and INSIDE into one networking event dedicated to the preparation of project proposals







Action	Title	Maximum JU Funding (M€)
HORIZON-Chips 2024-1-IA-T1	Global IA call according to SRIA 2024	103.00
HORIZON-Chips 2024-1-IA-T2	Focus topic on "High Performance RISC-V Automotive Processors supporting SDV"	20.00
HORIZON-Chips 2024-1-IA-T3	Focus topic on "Service Oriented Framework for the Software Defined Vehicle of the future"	20.00
HORIZON- Chips 2024-2-RIA-T1	Global RIA call according to SRIA 2023	52.00
HORIZON- Chips 2024-2-RIA-T2	Focus topic on "Sustainable and greener manufacturing"	15.00
HORIZON- Chips 2024-3-RIA *	Joint call with Korea on Heterogeneous integration and neuromorphic computing technologies for future semiconductor components and systems	6.00
* F th - C-112024 2 th ' DO	abara anti an EDD abara with a desilina an 4.4.4	216.00







Calls 2024

Call	Proposals	Total requested funding	Available funding
Global IA	13	€ 214.5M	€ 103M
Focus IA	1		
Global RIA	21	€ 187,2M	€ 52M
RIA focus 1	1		
RIA focus 2	1		





Italy in the Chips Act





Nasce a Pavia la Fondazione Chips.IT

Il Centro italiano per il design dei circuiti integrati a semiconduttori, coordinerà attività di ricerca e design con attori pubblici e privati, mettendo a disposizione attrezzature e software di ultima generazione.



Contratti di sviluppo – Nuovo sportello Semiconduttori



3,3 Miliardi di euro di contributi a fondo perduto e finanziamento agevolato per sostenere la crescita e lo sviluppo tecnologico della catena di approvvigionamento dei semiconduttori



Un nuovo fab di STM a Catania per i semiconduttori a largo gap.



Un nuovo sito di Silicon Box a Novara per advanced packaging.



Contratti di sviluppo





Contratti di sviluppo – Nuovo sportello Semiconduttori



Il 30 aprile apre un nuovo sportello per la presentazione di domande a valere sullo strumento agevolativo dei Contratti di sviluppo, dedicato allo sviluppo della filiera nazionale dei semiconduttori. Alla misura sono destinate le risorse del Fondo istituito dall'articolo 23, comma 1 del decreto-legge 1° marzo 2022, n. 17, che ha una dotazione di 3,292 miliardi di euro.

Cosa finanzia

- sviluppo dell'industria nazionale dei semiconduttori, nelle diverse fasi che ne compongono il processo di produzione;
- crescita e sviluppo tecnologico delle imprese appartenenti alla catena di approvvigionamento dei semiconduttori.

https://www.mimit.gov.it/it/incentivi/semiconduttori



A new fab in Sicily





Urso e Vestager a Catania per il nuovo impianto STMicroelectronics, 5 miliardi di investimento

31 Maggio 2024



Con questo nuovo sito la società annuncia un maxi investimento da 5 miliardi di euro per il nuovo stabilimento produttivo che offrirà nel capoluogo etneo 2000 posti di lavoro, con un sostegno finanziario di circa 2 miliardi di euro da parte dello Stato italiano nel quadro del Chips Act.

Il nuovo sito contribuirà a rafforzare la sicurezza nell'approvvigionamento, la resilienza e la sovranità digitale dell'Europa nei **semiconduttori** e avrà come focus produttivo la realizzazione in grandi volumi di carburo di silicio per dispositivi e moduli di potenza, nonché per attività di test e packaging.



Chiplets in Novara





Silicon Box sceglie Novara per il nuovo maxi impianto per la produzione di chiplet, investimento da 3,2 miliardi



Silicon Box ha scelto Novara, in Piemonte, come sede del suo nuovo maxi-impianto produttivo per la realizzazione di chiplet integration e advanced packaging e testing foundry, il primo nel suo genere in Europa per un investimento complessivo di 3,2 miliardi di euro.



Chips Mirror Group Italy: What can we do for you?



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- Disseminate information on Chips JU events and calls.
- Keep informed on future Chips JU and Chips Act initiatives and on running project proposals
- Collect project ideas and presentation of partners' competences for future brokerage events.
- Provide support and advice in the search for projects partners and in proposal preparation.







Follow us on the web sites



In addition to the previous web site, hosted by AEIT at:

https://www.aeit.it/ecsel,

a new web site is available at:

https://www.chips-mgi.it/









Thank you!

http://www.aeit.it/ecsel

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Steering Committee



























